

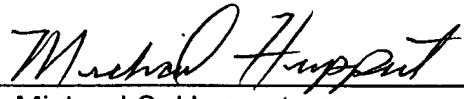
**REMARKS**

This amendment is submitted to correct a minor error in claim 46. No new matter has been added. A copy of the amended portion of claim 46, with changes marked therein, is attached and entitled "Version with markings to show changes made."

Accordingly, entry of the amendment is requested.

Respectfully submitted,

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46.(Amended) An electronic component mounting method comprising:  
mounting an electronic component (1) on a circuit board (4)  
while aligning in position an electrode of the electronic component (1) and an electrode  
(5) of the circuit board (4) in a state in which the electrode (2) of the electronic  
component (1) has a bump (3, 103) with interposition of an anisotropic conductive layer  
(10) in which an insulating resin mixed with an inorganic filler is mixed with a  
conductive particle (10a); and

subsequently bonding the electronic component to the circuit board  
by hardening the insulating resin of the anisotropic conductive layer interposed  
between the electronic component and the circuit board while correcting warp of the  
board with a pressure force applied to the electronic component against the circuit  
board by means of a tool (8) and heat applied from the electronic component side or  
heat applied from the board side or heat applied from both the electronic component  
side and the board side, so that the electrode of the electronic component is electrically  
connected with the electrode of the circuit board.

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